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12-bit Address Comparator



ADE-205-527 (Z) 1st. Edition Sep. 2000

Description

The HD74HC680 address comparator simplifies addressing of memory boards and/or other peripheral devices. The four P inputs are normally hard wired with a preprogrammed address. An internal decoder determines what input information applied to the 12 A inputs must be low or high to cause a low state at the output (Y). For example, a positive-logic bit combination of 0111 (decimal 7) at the P input determines that inputs A_1 through A_7 must be low and that inputs A_8 through A_{12} must be high to cause the output to go low. Equality of the address applied at the A inputs to the preprogrammed address is indicated by the output being low.

The HD74HC680 features a transparent latch and a latch enable input (C). When C is high, the device is in the transparent mode. When C is low, the previous logical state of Y is latched.

Features

High Speed Operation

• High Output Current: Fanout of 10 LSTTL Loads

• Wide Operating Voltage: $V_{CC} = 2$ to 6 V

• Low Input Current: 1 μA max

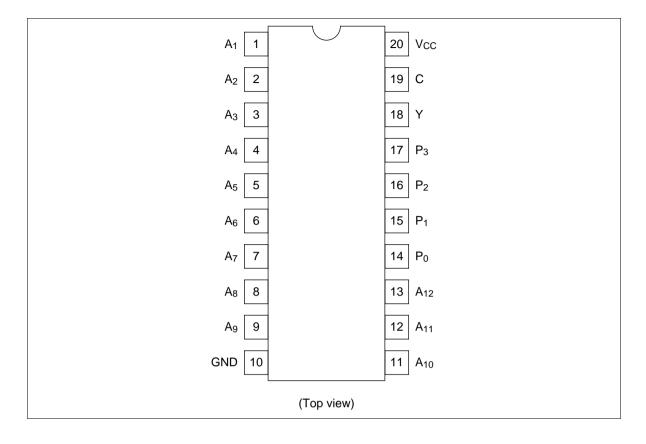
• Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (Ta = 25°C)

Function Table

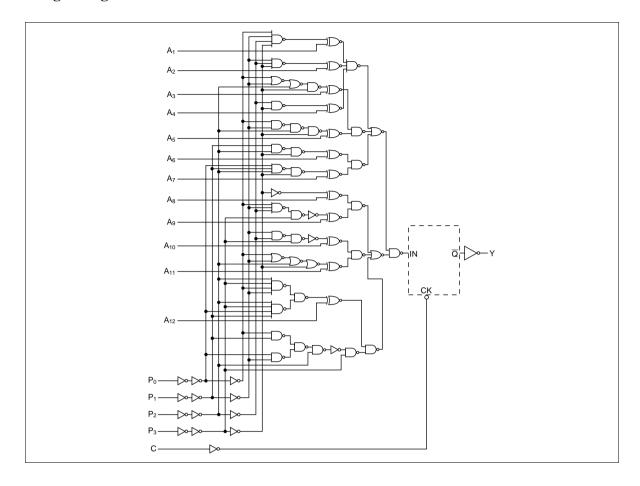
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•••	. 1	•	

С	P ₃	P ₂	P ₁	P ₀	A ₁	A ₂	A_3	A_4	A_5	A_6	A ₇	A ₈	A ₉	A ₁₀	A ₁₁	A ₁₂	Output Y
Н	L	L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L
Н	L	L	L	Н	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L
Н	L	L	Н	L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L
Н	L	L	Н	Н	L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	L
Н	L	Н	L	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н	Н	L
Н	L	Н	L	Н	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н	L
Н	L	Н	Н	L	L	L	L	L	L	L	Н	Н	Н	Н	Н	Н	L
Н	L	Н	Н	Н	L	L	L	L	L	L	L	Н	Н	Н	Н	Н	L
Н	Н	L	L	L	L	L	L	L	L	L	L	L	Н	Н	Н	Н	L
Н	Н	L	L	Н	L	L	L	L	L	L	L	L	L	Н	Н	Н	L
Н	Н	L	Н	L	L	L	L	L	L	L	L	L	L	L	Н	Н	L
Н	Н	L	Н	Н	L	L	L	L	L	L	L	L	L	L	L	Н	L
Н	Н	Н	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L
Н	Н	Н	L	Н	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Н
Н	Н	Н	Н	L	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Χ	Н
Н	Н	Н	Н	Н	L	L	L	L	L	L	L	L	L	L	L	L	L
Н	H All other combinations										Н						
L	L Any combination									Latched							

Pin Arrangement



Logic Diagram



DC Characteristics

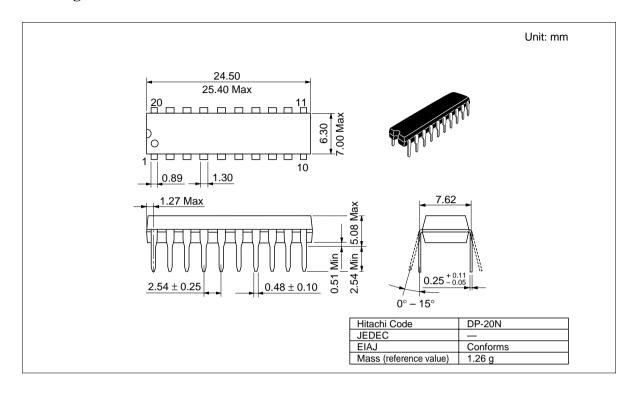
			Ta = 25°C		Ta = -40 to +85°C					
Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Condition	ns
Input voltage	V _{IH}	2.0	1.5	_	_	1.5	_	V		
		4.5	3.15	<u> </u>	_	3.15	_	_		
		6.0	4.2	_	_	4.2	_	_		
	V _{IL}	2.0	_	_	0.5	_	0.5	V		
		4.5	_	_	1.35	_	1.35	_		
		6.0	_	_	1.8	_	1.8	=		
Output voltage	V _{OH}	2.0	1.9	2.0	_	1.9	_	V	Vin = V _{IH} or V _{IL}	$I_{OH} = -20 \mu A$
		4.5	4.4	4.5	_	4.4	_	_		
		6.0	5.9	6.0	_	5.9	_	=		
		4.5	4.18	s —	_	4.13	_	-		$I_{OH} = -4 \text{ mA}$
		6.0	5.68	3 —	_	5.63	_	=		$I_{OH} = -5.2 \text{ mA}$
	V _{OL}	2.0	_	0.0	0.1	_	0.1	V	Vin = V _{IH} or V _{IL}	I _{OL} = 20 μA
		4.5	_	0.0	0.1	_	0.1	=		
		6.0	_	0.0	0.1	_	0.1	=		
		4.5	_	_	0.26	_	0.33	=		I _{OL} = 4 mA
		6.0	_	_	0.26	_	0.33	-		I _{OL} = 5.2 mA
Input current	lin	6.0	_	_	±0.1	_	±1.0	μΑ	Vin = V _{CC} or GI	ND
Quiescent supply current	I _{cc}	6.0	_	_	4.0	_	40	μΑ	Vin = V _{CC} or Gi	ND, lout = $0 \mu A$

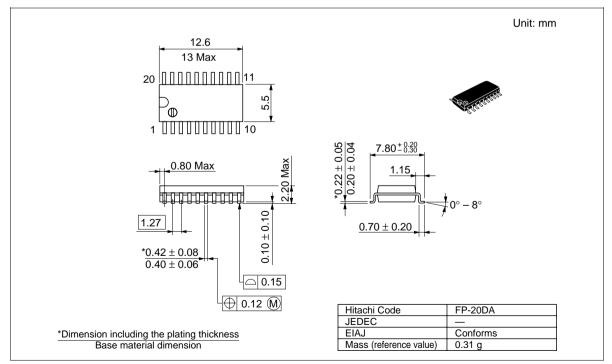
AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

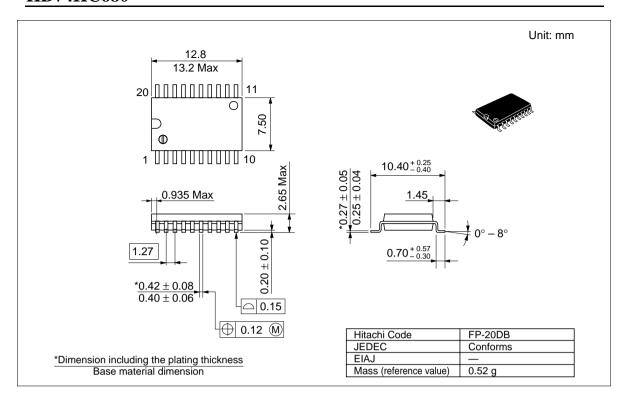
Ta = -40 to $Ta = 25^{\circ}C$ +85°C

Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Propagation delay	t _{PLH}	2.0	_	_	330	_	410	ns	P to Y
time	t _{PHL}	4.5	_	26	66	_	82	_	
		6.0	_	_	56	_	70	-	
	t _{PLH}	2.0	_	_	210	_	265	ns	A to Y
	t _{PHL}	4.5	_	19	42	_	53	_	
		6.0	_	_	36	_	45	-	
	t _{PLH}	2.0	_	_	150	_	190	ns	C to Y
	t _{PHL}	4.5	_	18	30	_	38	_	
		6.0	_	_	26	_	33	=	
Setup time	t _{su}	2.0	100	_	_	125	_	ns	A to C
		4.5	20	12	_	25	_	_	
		6.0	17	_	_	21	_	=	
Output rise/fall	t _{TLH}	2.0	_	_	75	_	95	ns	
time	t_{THL}	4.5	_	6	15	_	19	=	
		6.0	_	_	13	_	16	_	
Input capacitance	Cin	_	_	5	10	_	10	pF	

Package Dimensions







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